

2N7002K

N-Channel MOSFET

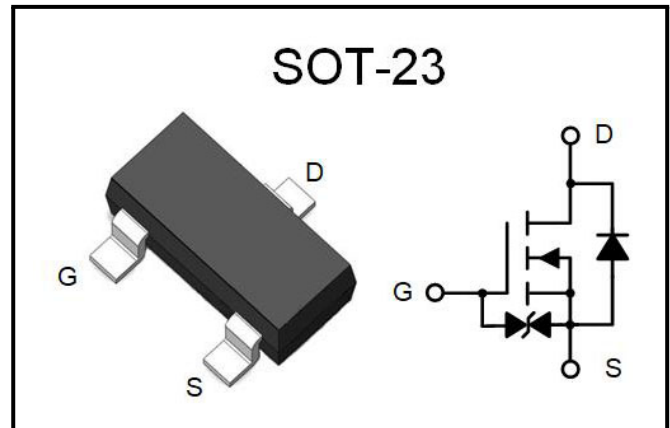
Features

- $V_{DS}=60V$
- $I_D=0.3A$
- $R_{DS(ON)}@V_{GS}=10V, MAX=3\Omega$
- $R_{DS(ON)}@V_{GS}=4.5V, MAX=4\Omega$

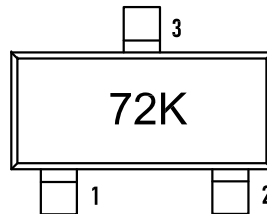
Description

- Super High dense cell design for extremely low $R_{DS(ON)}$
- Reliable and Rugged
- SOT-23 for Surface Mount Package
- ESD protected

Package



Marking



Ordering information

Order code	Package	Marking	Base qty	Delivery mode
2N7002K	SOT-23	72K	3K	Tape and reel

Absolute Maximum Ratings (@ $T_A=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	0.3	A
P_D	Maximum Power Dissipation	0.225	W
T_J	Junction Temperature	150	$^{\circ}C$
T_{stg}	Storage Temperature	-55 to + 150	$^{\circ}C$
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance	556	$^{\circ}C/W$



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Electrical Characteristics @T_A=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250uA	60	—	—	V
V _{GS(th)}	Gate Threshold Voltage ⁽¹⁾	V _{DS} = V _{GS} , I _D = 250uA	1	1.5	2.5	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 48V, V _{GS} = 0V	—	—	1	uA
I _{GSS1}	Gate-Source Leakage Current	V _{GS} = ±20V, V _{DS} = 0V	—	—	±10	uA
I _{GSS2}		V _{GS} = ±10V, V _{DS} = 0V	—	—	±200	nA
I _{GSS3}		V _{GS} = ±5V, V _{DS} = 0V	—	—	±100	nA
R _{DS(on)}	Drain-Source On-Resistance ⁽¹⁾	V _{GS} = 4.5V, I _D = 200mA	—	—	4.0	Ω
		V _{GS} = 10V, I _D = 300mA	—	—	3.0	
V _{SD}	Diode Forward Voltage	V _{GS} = 0V, I _S = 200mA	—	—	1.2	V
Q _r	Recovered Charge	V _{GS} = 0V, I _S = 300mA, V _R = 25V, dI _S /dI _t = -100A/uS	—	30	—	nC
Dynamic ⁽²⁾						
C _{iss}	Input Capacitance	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz	—	—	40	pF
C _{oss}	Output Capacitance		—	—	30	
C _{rss}	Reverse Transfer Capacitance		—	—	10	
Switching ⁽²⁾						
t _{d(on)}	Turn-on Delay Time	V _{DS} = 10V, V _{DD} = 50V, R _G = 50Ω, R _{GS} = 50Ω, R _L = 250Ω	—	—	10	nS
t _{d(off)}	Turn-off Delay Time		—	—	15	
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 300mA, V _R = 25V, dI _S /dI _t = -100A/uS	—	30	—	nS
GATE-SOURCE ZENER DIODE						
BV _{GSO}	Gate-Source Breakdown Voltage	I _{gs} = ±1mA(Open Drain)	±21.5	—	±30	V

Notes:

(1) Pulse Test : Pulse Width ≤300% , Duty Cycle ≤2%

(2) These parameters have no way to verify.



Typical Performance Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Figure 1 :Output Characteristics

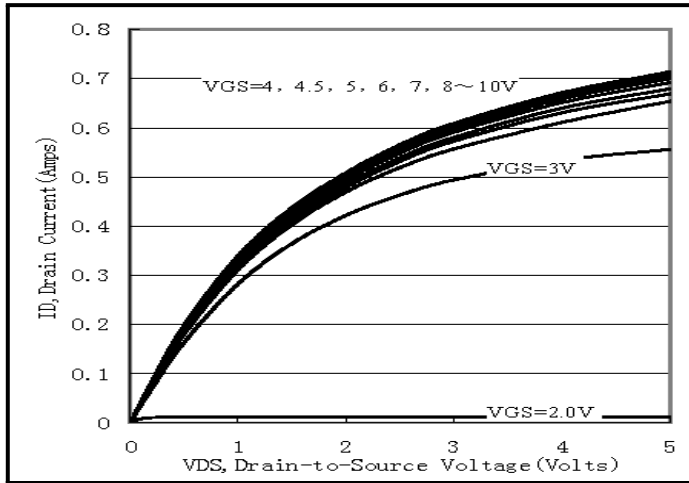


Figure 2 :Transfer Characteristics

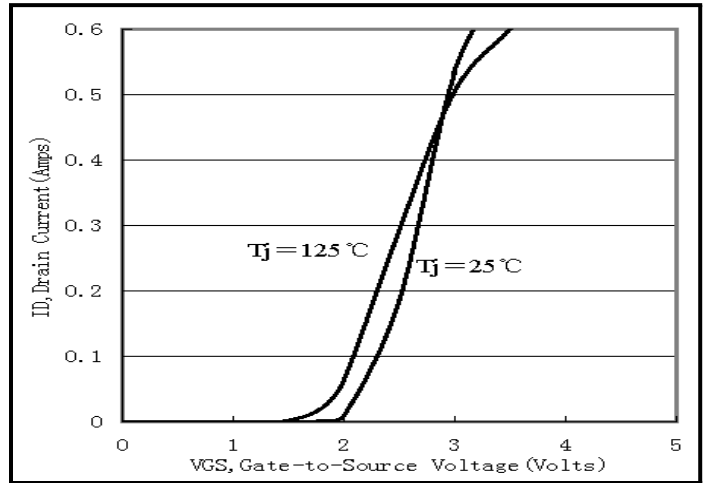


Figure 3 :Breakdown Voltage Variation Temperature

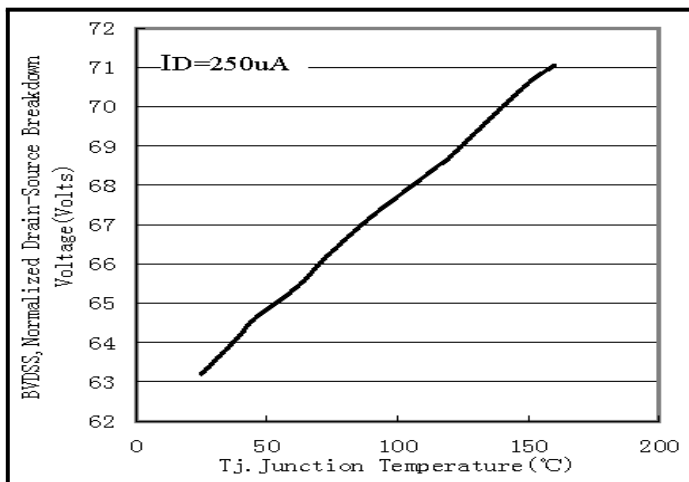
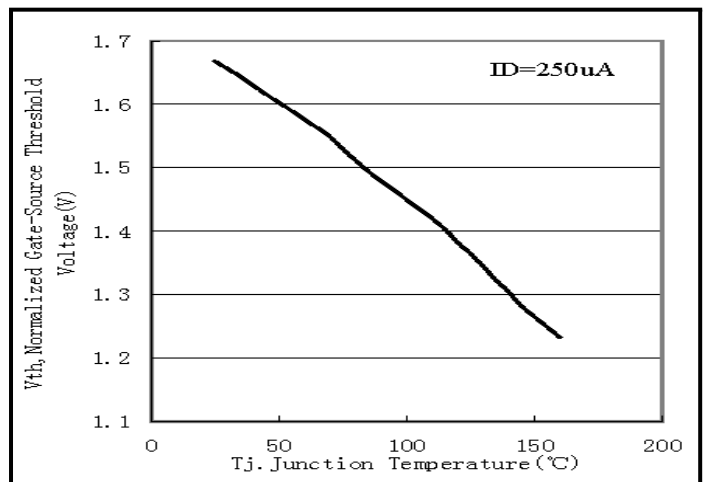


Figure 4 :Gate Threshold Variation Temperature



Typical Performance Characteristics($T_J = 25^\circ\text{C}$, unless otherwise noted)

Figure 5 :On-Resistance Variation with Temperature

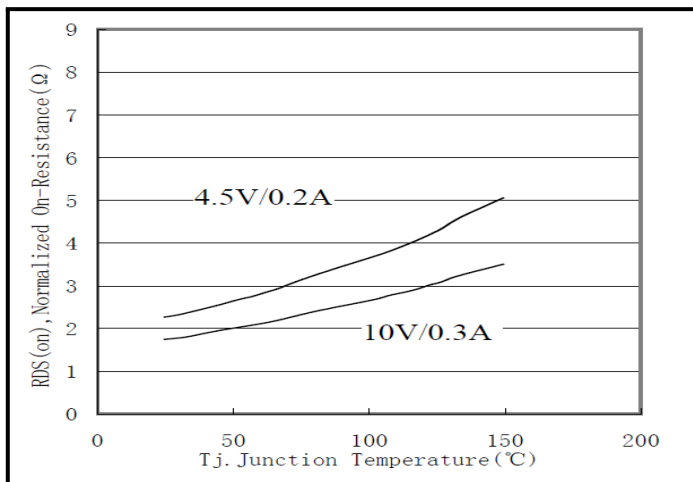


Figure 6 : On-Resistance vs. Drain Current

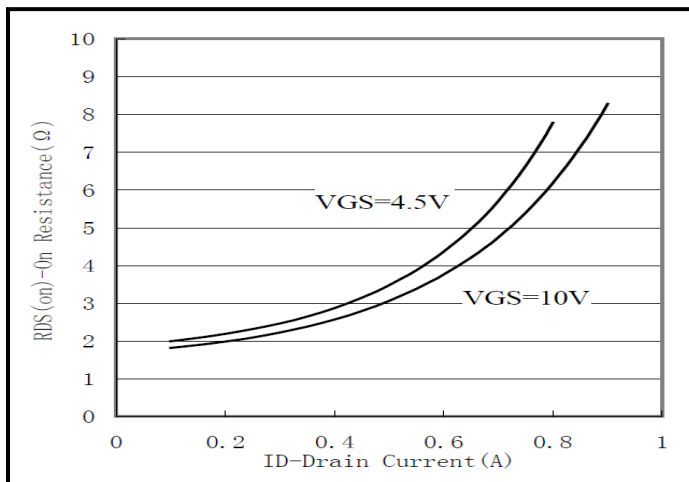


Figure 7 :On-Resistance vs. Gate-to-Source Voltage

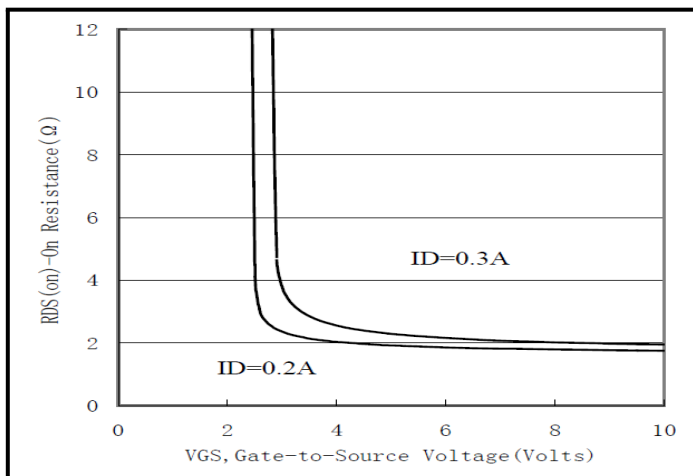
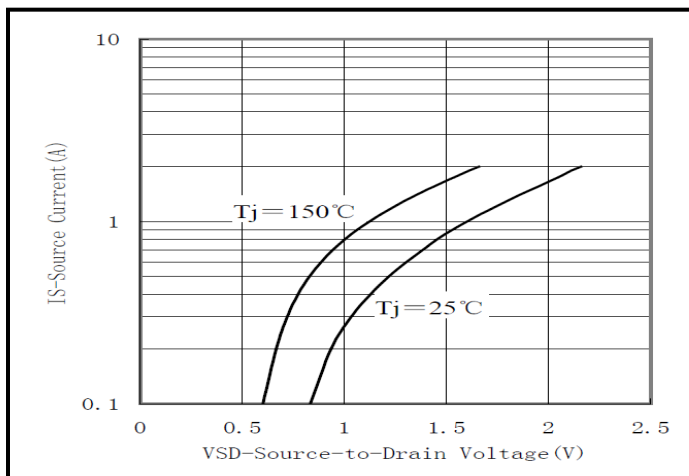


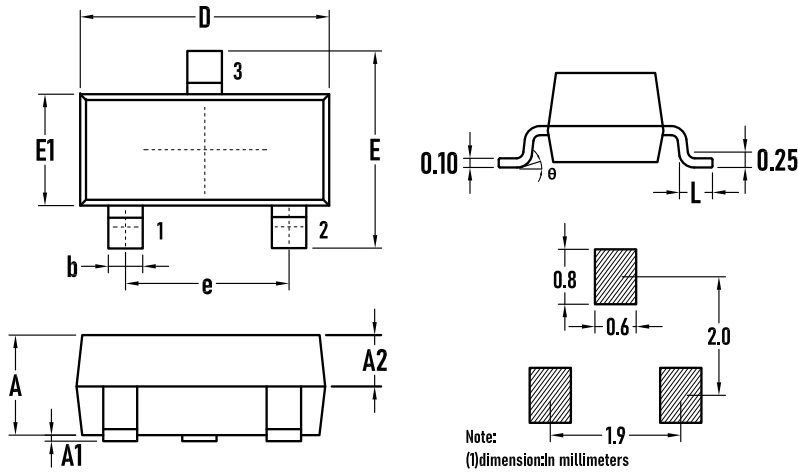
Figure 8 :Source-Drain Diode Forward Voltage



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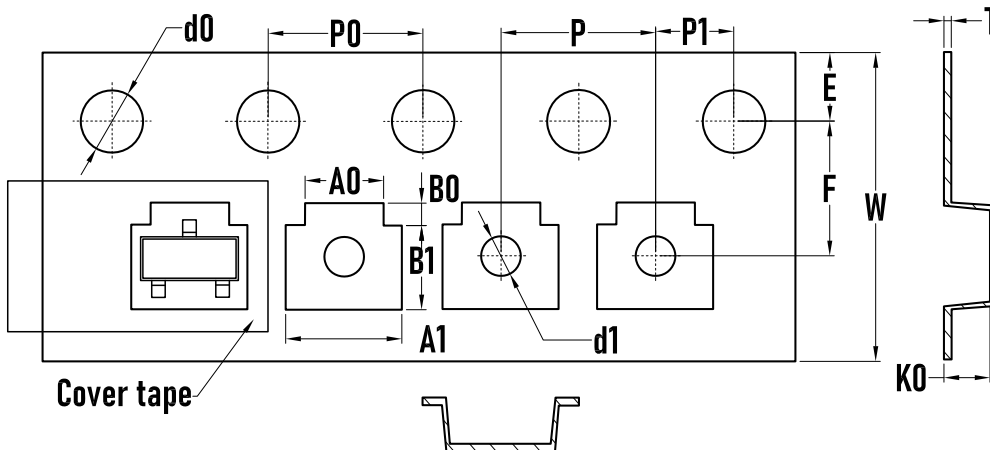
N-Channel MOSFET

Outline Drawing - SOT-23



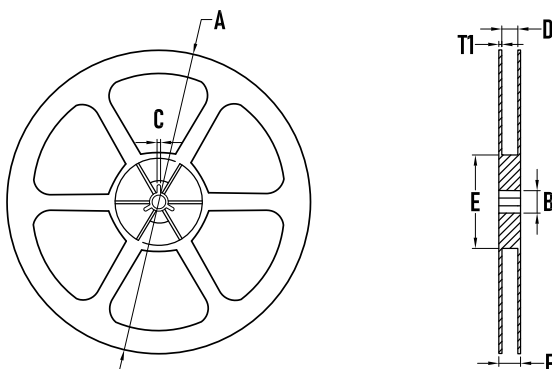
SYMBOL	MILLIMETER		
	MIN.	Typ.	MAX.
A	0.90	1.00	1.10
A1	0.01	—	0.10
A2	0.50	0.60	0.70
D	2.80	2.90	3.00
b	0.25	0.35	0.45
E	2.10	2.30	2.50
E1	1.20	1.30	1.40
e	1.80	1.90	2.00
L	0.25	0.35	0.45
θ	0	—	8°

Packaging Tape - SOT-23



SYMBOL	MILLIMETER
A0	2.10±0.10
A1	3.10±0.10
B0	0.65±0.10
B1	2.75±0.10
d0	1.55±0.10
d1	1.00±0.05
E	1.75±0.10
F	3.50±0.10
K0	1.10±0.10
P	4.00±0.10
P0	4.00±0.10
P1	2.00±0.10
W	8.00±0.30
T	0.20 ±0.05

Packaging Reel



SYMBOL	MILLIMETER
A	177.8±0.2
B	3.1
C	13.50
D	9.6±0.3
E	75±0.2
F	12.3±0.3
T1	1.0±0.2
Quantity	3000PCS

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Specifications are subject to change without notice.

Please refer to <http://www.born-tw.com> for current information.

Revision: 2022-Jan-1-A

